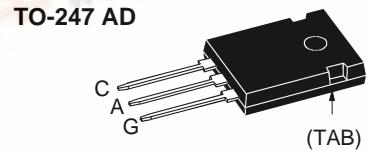


Phase Control Thyristor

$V_{RRM} = 1200-1600 \text{ V}$
 $I_{T(RMS)} = 30 \text{ A}$
 $I_{T(AV)M} = 19 \text{ A}$

V_{RSM} V_{DSM}	V_{RRM} V_{DRM}	Type
V	V	
1200	1200	CS 20-12io1
1400	1400	CS 20-14io1
1600	1600	CS 20-16io1



C = Cathode, A = Anode, G = Gate
TAB = Anode

Symbol	Test Conditions	Maximum Ratings		Features
$I_{T(RMS)}$ $I_{T(AV)M}$	$T_{VJ} = T_{VJM}$ $T_{case} = 85^\circ\text{C}$; 180° sine	30	A	<ul style="list-style-type: none"> Thyristor for line frequency International standard package JEDEC TO-247 Planar passivated chip Long-term stability of blocking currents and voltages Epoxy meets UL 94V-0
	$T_{VJ} = 45^\circ\text{C}$; $V_R = 0 \text{ V}$	19	A	
I_{TSM}	$t = 10 \text{ ms}$ (50 Hz), sine	200	A	<ul style="list-style-type: none"> Motor control Power converter AC power controller Switch-mode and resonant mode power supplies Light and temperature control
	$t = 8.3 \text{ ms}$ (60 Hz), sine	215	A	
I^{2t}	$T_{VJ} = T_{VJM}$ $V_R = 0 \text{ V}$	180	A	<ul style="list-style-type: none"> Space and weight savings Simple mounting Improved temperature and power cycling
	$t = 10 \text{ ms}$ (50 Hz), sine $t = 8.3 \text{ ms}$ (60 Hz), sine	195	A	
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM}$ $f = 50 \text{ Hz}$, $t_p = 200 \mu\text{s}$	200	A^2s	<ul style="list-style-type: none"> Easy to mount with 1 screw (isolated mounting screw hole) Improved temperature and power cycling
	$V_D = 2/3 V_{DRM}$ $I_G = 0.3 \text{ A}$ $di_G/dt = 0.3 \text{ A}/\mu\text{s}$	195	A^2s	
$(di/dt)_{cr}$	repetitive, $I_T = 40 \text{ A}$	162	A^2s	<ul style="list-style-type: none"> Improved temperature and power cycling
	non repetitive, $I_T = I_{T(AV)M}$	158	A^2s	
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM}$; $R_{GK} = \infty$; method 1 (linear voltage rise)	150	$\text{A}/\mu\text{s}$	<ul style="list-style-type: none"> Improved temperature and power cycling
	$V_{DR} = 2/3 V_{DRM}$	500	$\text{A}/\mu\text{s}$	
P_{GM}	$T_{VJ} = T_{VJM}$ $I_T = I_{T(AV)M}$	1000	$\text{V}/\mu\text{s}$	<ul style="list-style-type: none"> Improved temperature and power cycling
	$t_p = 30 \mu\text{s}$ $t_p = 300 \mu\text{s}$	10	W	
P_{GAV}		5	W	<ul style="list-style-type: none"> Improved temperature and power cycling
		0.5	W	
V_{RGM}		10	V	
T_{VJ} T_{VJM} T_{stg}		-40...+125	$^\circ\text{C}$	<ul style="list-style-type: none"> Improved temperature and power cycling
		125	$^\circ\text{C}$	
		-40...+125	$^\circ\text{C}$	
M_d Weight	Mounting torque M3	0.8...1.2	Nm	<ul style="list-style-type: none"> Improved temperature and power cycling
		6	g	

Data according to IEC 60747
IXYS reserves the right to change limits, test conditions and dimensions

Symbol	Test Conditions	Characteristic Values			
I_R, I_D	$T_{VJ} = T_{VJM}$; $V_R = V_{RRM}$; $V_D = V_{DRM}$	≤	2	mA	
V_T	$I_T = 25 \text{ A}$; $T_{VJ} = 25^\circ\text{C}$	≤	2.1	V	
V_{TO}	For power-loss calculations only ($T_{VJ} = 125^\circ\text{C}$)	1.1		V	
r_T		40		$\text{m}\Omega$	
V_{GT}	$V_D = 6 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	≤	1.0	V	
I_{GT}	$V_D = 6 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	≤	65	mA	
V_{GD}	$T_{VJ} = T_{VJM}$;	$V_D = 2/3 V_{DRM}$	≤	0.2	V
I_{GD}			≤	5	mA
I_L	$T_{VJ} = 25^\circ\text{C}$; $t_p = 10 \mu\text{s}$ $I_G = 0.3 \text{ A}$; $di_G/dt = 0.3 \text{ A}/\mu\text{s}$	≤	150	mA	
I_H	$T_{VJ} = 25^\circ\text{C}$; $V_D = 6 \text{ V}$; $R_{GK} = \infty$	≤	100	mA	
t_{gd}	$T_{VJ} = 25^\circ\text{C}$; $V_D = 1/2 V_{DRM}$ $I_G = 0.3 \text{ A}$; $di_G/dt = 0.3 \text{ A}/\mu\text{s}$	≤	2	μs	
R_{thJC}	DC current		0.62	K/W	
R_{thJH}	DC current		0.82	K/W	
a	Max. acceleration, 50 Hz		50	m/s^2	

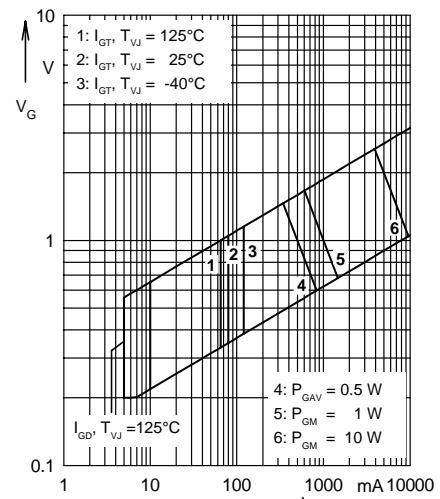
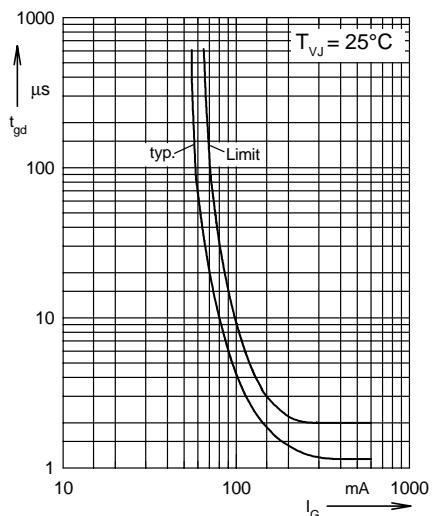
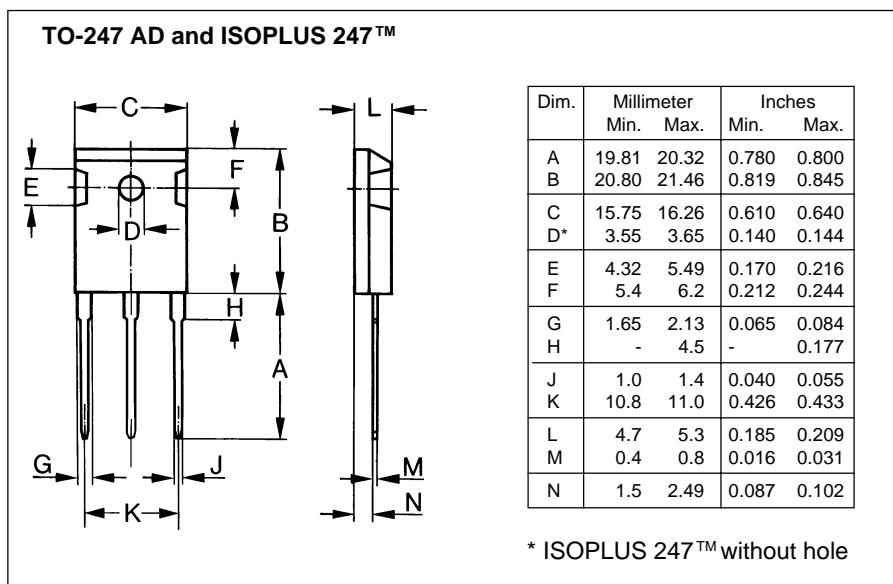


Fig. 1 Gate trigger range


Fig. 2 Gate controlled delay time t_{gd}


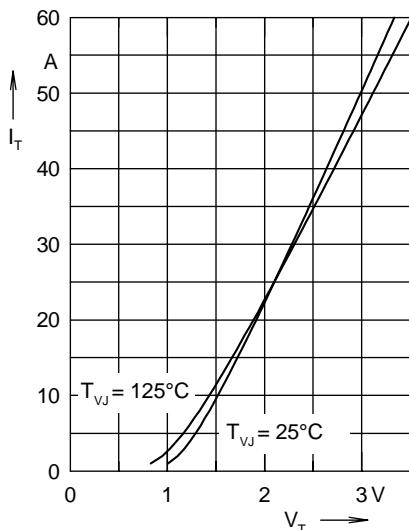


Fig. 3 Forward characteristics

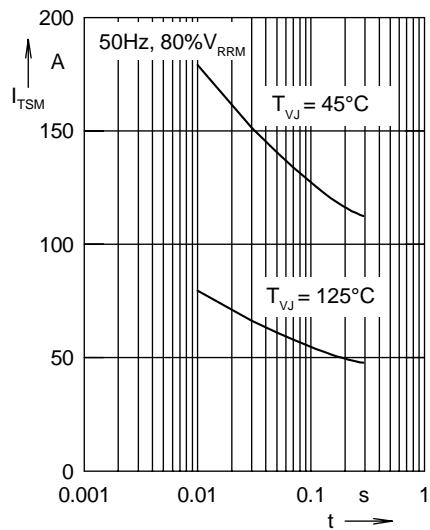


Fig. 4 Surge overload current
 $I_{TS M}$: crest value, t : duration

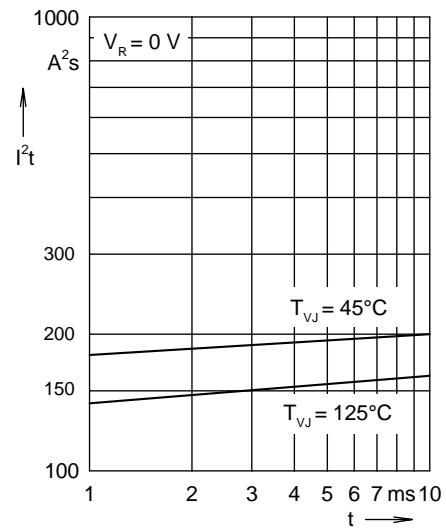


Fig. 5 I^2t versus time (1-10 ms)

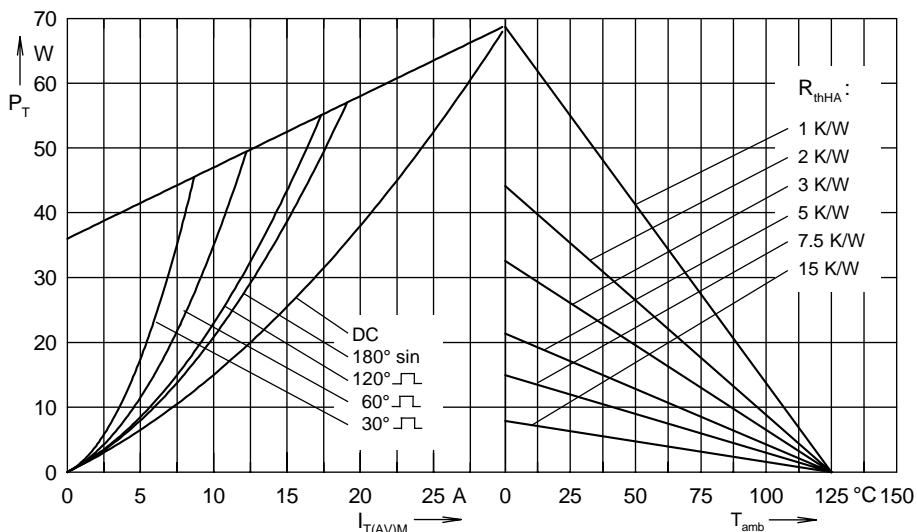


Fig. 6 Power dissipation versus forward current and ambient temperature

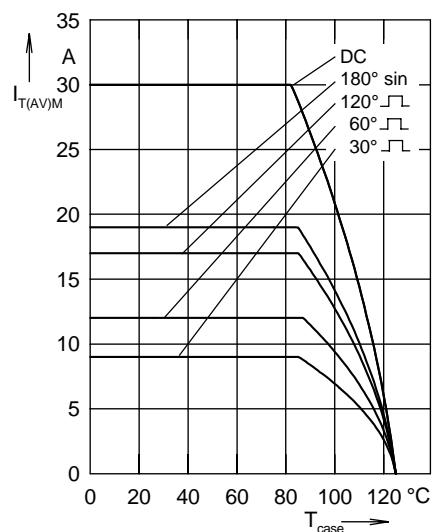


Fig. 7 Max. forward current at case temperature

R_{thJC} for various conduction angles d :

d	R_{thJC} (K/W)
DC	0.62
180°	0.71
120°	0.748
60°	0.793
30°	0.817

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.206	0.013
2	0.362	0.118
3	0.052	1.488

Fig. 8 Transient thermal impedance junction to case